Polishing Process Recommendation

Company profile

+ ABOUT US

Shaoxing Ziyuan Polishing Co., Ltd.

Shaoxing Ziyuan Polishing Co., Ltd. was established in 2012 to develop abrasive
industry in China. We are committed to research and manufacture of paper abr
products, lapping film, structural abrasive products, foamdisc, microfinishing fi
polishing slurry and compounds. We have a professional research team with ric
experience and we keep strong investment in developing new products and qu
systems for metal working, AOEM, AAM, wood working, glass, ceramic and nonf
metal, etc. We have applied 16 patents and have our core advantages in techn
advanced production line, timely service and professional all-in-one solutions.
products are widely applied in fiber optical, micro motor, LCD, roller, automobi
3C industry and the customers are worldwide including USA, United Kingdom,
Italy, India, Israel, Brazil, Argentina, Russia etc. We have the goal to supply the hi
products to the global market and sincerely welcome customers worldwide to
us. We can provide OEM, ODM and One- stop service for you.We are young, You
yuan fang lai, Bu yi Le hu(有朋自远方来，不亦乐乎)，it is a delight thing when
come together from afar. We are willing to share our value of trust, cooperation,
and teamwork, we are chasing a win-win situation with our guest, and we are
to have a bright future.

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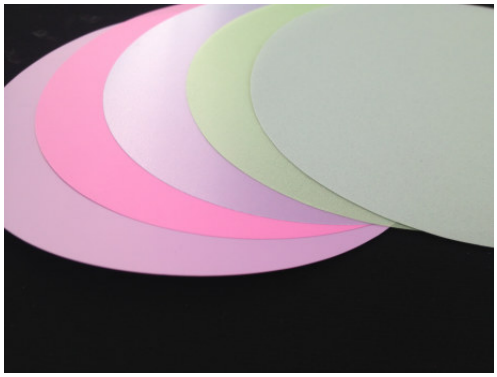
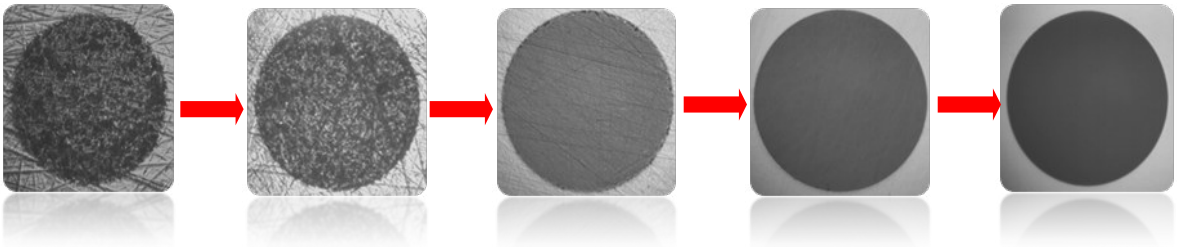
ZYPOLISH

Polishing Process Recommendation



No.1 Seiko Giken SFP-550：

Step		Polishing Film			Process			
		Micron	Mineral	Product ID	Pressure	Pad	Liquid	Time
1	Remove Epoxy	15/30	SiC/D	SC15/SC30/ D30	By hand	70 D	Dry	30-45s
	Cleaning							
2	Rough Polishing	9	Diamond	D9	Clamps	80 D	DI water	20-40s
	Cleaning							
3	Middle Polishing	3	Diamond	D3	Clamps	80 D	DI water	20-40s
	Cleaning							
4	Fine Polishing	1	Diamond	D1	Clamps	80 D	DI water	20-40s
	Cleaning							
5	Final Polishing	0.01	SiO2	ADS	Clamps	70 D	DI water/ SOQ-12D	20-30s
	Cleaning							



Remove Epoxy *Rough Polishing* *Middle Polishing* *Fine Polishing* *Final Polishing*

Note:

In the grinding process, cleaning is very important. Effective cleaning can improve the yield and production efficiency of the product.

This process is for reference only. The customer process also needs to be fine-tuned on site according to the different equipment, operation and 3D data of each customer.

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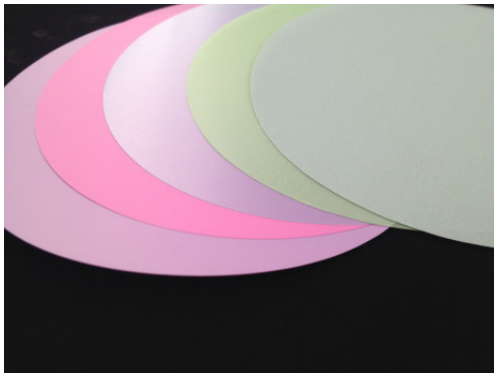
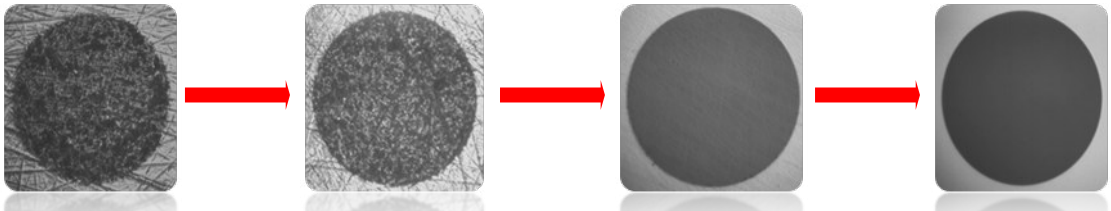


Seiko Giken SFP-550

:

Step		Polishing Film			Process			
		Micron	Mineral	Product ID	Pressure	Pad	Liquid	Time
1	Remove Epoxy	15/30	SiC/D	SC15/SC30/ D30	By hand	70 D	Dry	30-45s
	Cleaning							
2	Rough Polishing	9	Diamond	D9	Clamps	70/80 D	DI water	40-50s
	Cleaning							
3	Fine Polishing	1	Diamond	D1	Clamps	80 D	DI water	40-50s
	Cleaning							
4	Final Polishing	0.01	SiO2	ADS	Clamps	70 D	DI water/ SOQ-12D	20-30s
	Cleaning							



Remove Epoxy *Rough Polishing* *Fine Polishing* *Final Polishing*

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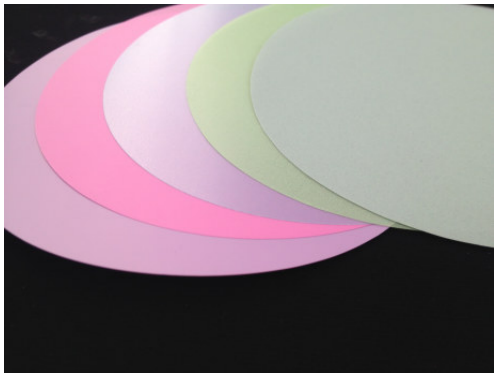
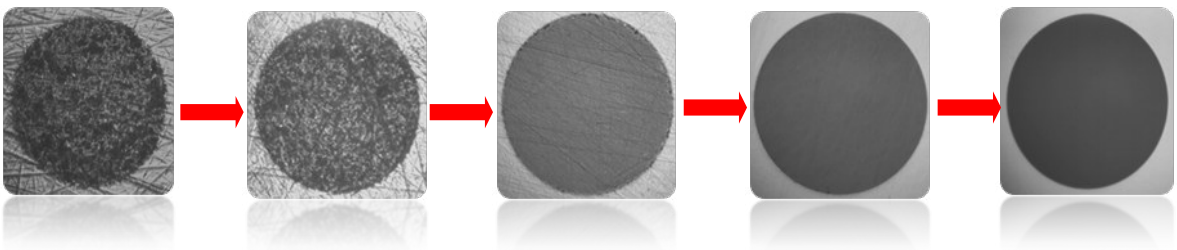


Seiko Instrument OFL-12(12UPC) :

Step		Polishing Film			Process				
		Micron	Mineral	Product ID	Pressure	Pad	Liquid	Speed	Time
1	Remove Epoxy	15/30	SiC/D	SC15/SC30 /D30	By hand	60 D	Dry	n/a	30-50s
	Cleaning								
2	Rough Polishing	9	Diamond	D9	Point 1	60 D	DI water	140-220rpm	30-50s
	Cleaning								
3	Middle Polishing	3	Diamond	D3	Point1	60 D	DI water	160-220rpm	30-50s
	Cleaning								
4	Fine Polishing	1	Diamond	D1	Point 1	60 D	DI water	160-220rpm	30-50s
	Cleaning								
5	Final Polishing	0.01	SiO2	ADS	Point0.5-1	55 D	DI water/ SOQ-12D	160-220rpm	30-40s
	Cleaning								



Remove Epoxy Polishing *Rough Polishing* *Middle Polishing* *Fine Polishing* *Final*

Note:

In the grinding process, cleaning is very important. Effective cleaning can improve the yield and production efficiency of the product.

The gear in the pressure is mainly aimed at grinding machines similar to OFL-12. The weight used is about 475g. The first gear is the second scale of the lever, that is, after the long scale.

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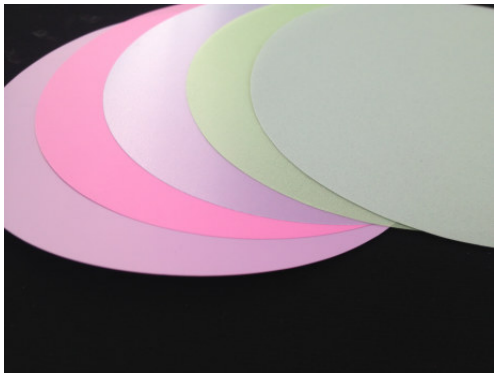
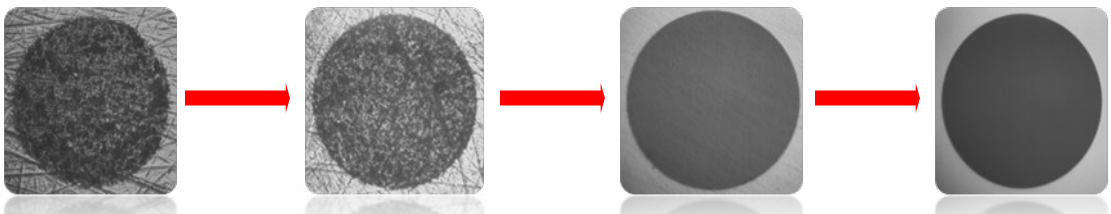


Seiko Instrument OFL-12(12UPC) :

Step		Polishing Film			Process				
		Micron	Mineral	Product ID	Pressure	Pad	Liquid	Speed	Time
1	Remove Epoxy	15/30	SiC/D	SC15/SC30 /D30	By hand	60 D	Dry	n/a	30-60s
	Cleaning								
2	Rough Polishing	9	Diamond	D9	Point 2	60 D	DI water	140-220rpm	40-60s
	Cleaning								
3	Fine Polishing	1	Diamond	D1	Point 2	60 D	DI water	160-220rpm	40-60s
	Cleaning								
4	Final Polishing	0.01	SiO2	ADS	Point 1	55 D	DI water/ SOQ-12D	160-220rpm	30-40s
	Cleaning								



Remove Epoxy *Rough Polishing* *Fine Polishing* *Final Polishing*

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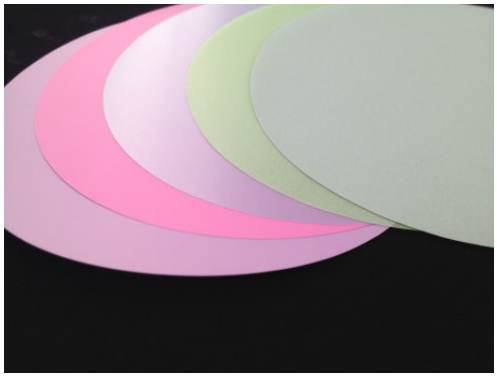
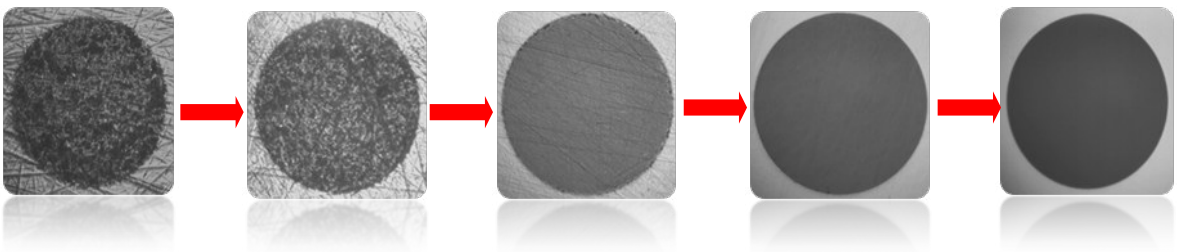


Domaille 18UPC :

Step		Polishing Film			Process				
		Micron	Mineral	Product ID	Pressure	Pad	Liquid	Speed	Time
1	Remove Epoxy	15/30	SiC/D	SC15/SC30 /D30	By hand	70 D	Dry	n/a	30-60s
	Cleaning								
2	Rough Polishing	9	Diamond	D9	120g/pc	80 D	DI water	160-220rpm	30-50s
	Cleaning								
3	Middle Polishing	3	Diamond	D3	150g/pc	80 D	DI water	160-220rpm	30-50s
	Cleaning								
4	Fine Polishing	1	Diamond	D1	150g/pc	80 D	DI water	160-220rpm	30-50s
	Cleaning								
5	Final Polishing	0.01	SiO2	ADS	150g/pc	70 D	DI water/ SOQ-12D	160-220rpm	30-50s
	Cleaning								



Remove Epoxy Polishing *Rough Polishing* *Middle Polishing* *Fine Polishing* *Final*

Note:

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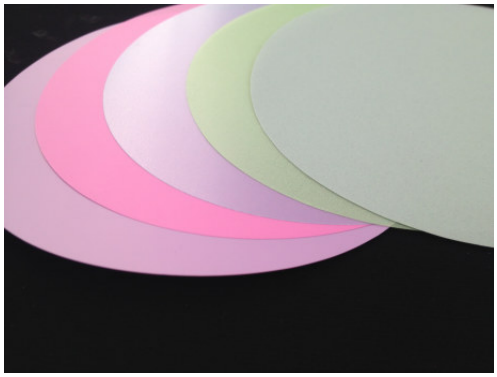
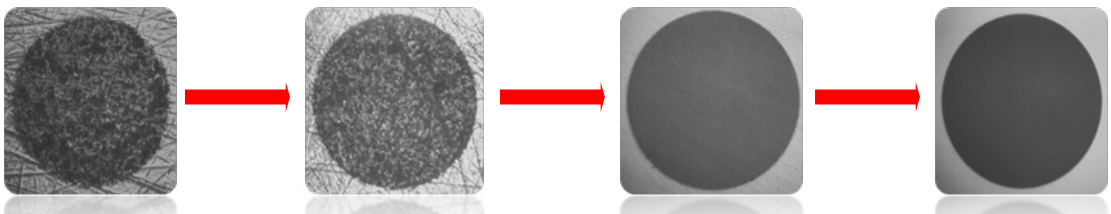


Domaille 18UPC :

Step		Polishing Film			Process				
		Micron	Mineral	Product ID	Pressure	Pad	Liquid	Speed	Time
1	Remove Epoxy	15	SiC	SC15	By hand	70 D	Dry	n/a	30-60s
	Cleaning								
2	Rough Polishing	9	Diamond	D9	150g/pc	80 D	DI water	160-220rpm	50-60s
	Cleaning								
4	Fine Polishing	1	Diamond	D1	150g/pc	80 D	DI water	160-220rpm	50-60s
	Cleaning								
5	Final Polishing	0.01	SiO2	ADS	150g/pc	70 D	DI water/ SOQ-12D	160-220rpm	40-60s
	Cleaning								



Remove Epoxy *Rough Polishing* *Fine Polishing* *Final Polishing*

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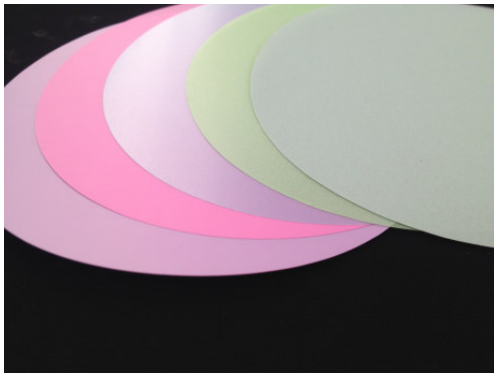
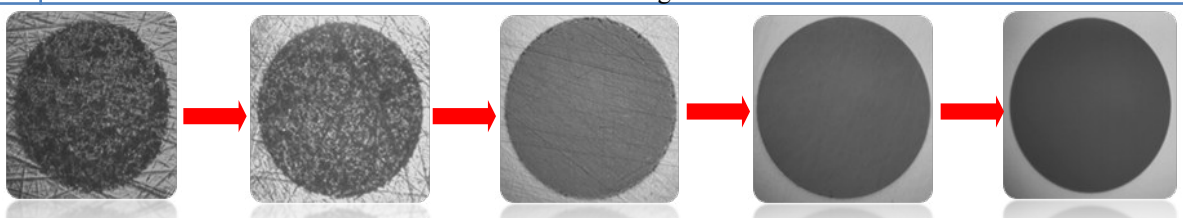


NANOMETER:

Step		Polishing Film			Process		
		Micron	Mineral	Product ID	Pad	Liquid	Time
1	Remove Epoxy	15/30	SiC/D	SC15/SC30/ D30	60 D	Dry	30-60
	Cleaning						
2	Rough Polishing	9	Diamond	D9	60 D	DI water	2min
	Cleaning						
3	Middle Polishing	3	Diamond	D3	60 D	DI water	1.5min
	Cleaning						
4	Fine Polishing	1	Diamond	D1	60 D	DI water	1.5min
	Cleaning						
5	Final Polishing	0.01	SiO2	ADS	50D	DI water/ SOQ-12D	1min
	Cleaning						



Remove Epoxy Polishing *Rough Polishing* *Middle Polishing* *Fine Polishing* *Final*

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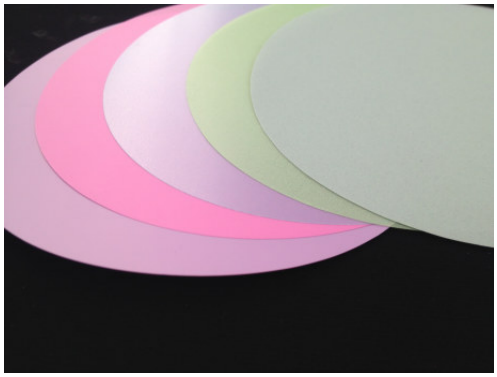
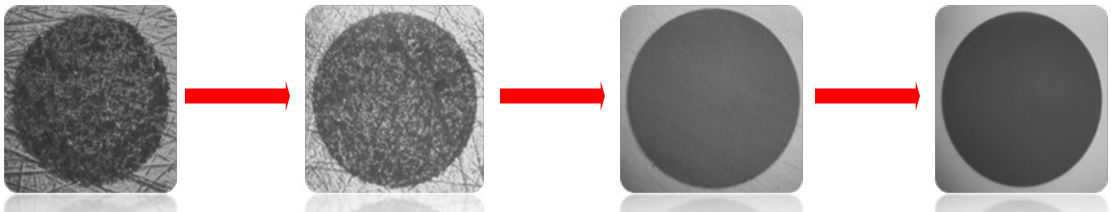


NANOMETER:

Step		Polishing Film			Process		
		Micron	Mineral	Product ID	Pad	Liquid	Time
1	Remove Epoxy	15/30	SiC/D	SC15/SC30 /D30	60 D	Dry	30-60s
	Cleaning						
2	Rough Polishing	9	Diamond	D9	60 D	DI water	2min
	Cleaning						
3	Fine Polishing	1	Diamond	D1	60 D	DI water	2min
	Cleaning						
4	Final Polishing	0.01	SiO2	ADS	50D	DI water/ SOQ-12D	1min
	Cleaning						



Remove Epoxy *Rough Polishing* *Fine Polishing* *Final Polishing*

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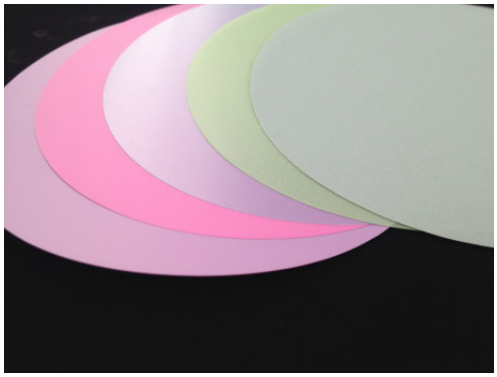
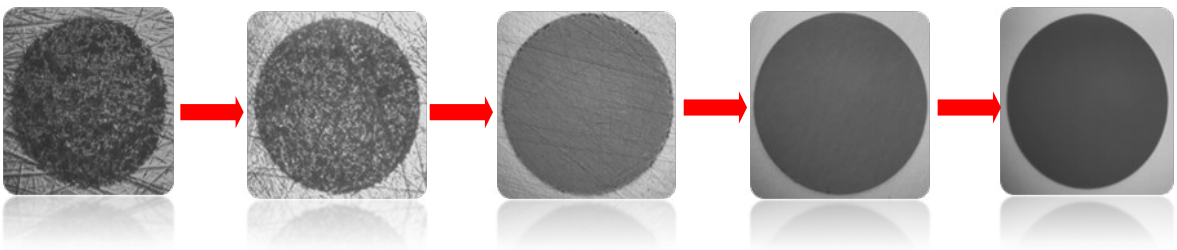


Seiko Instrument OFL-15(12UPC) :

Step		Polishing Film			Process				
		Micron	Mineral	Product ID	Pressure	Pad	Liquid	Speed	Time
1	Remove Epoxy	15	SiC	SC15	By hand	n/a	Dry	n/a	30-50s
	Cleaning								
2	Rough Polishing	9	Diamond	D9	1500g	60 D	DI water	160-220rpm	30-50s
	Cleaning								
3	Middle Polishing	3	Diamond	D3	1800g	60 D	DI water	160-220rpm	30-50s
	Cleaning								
4	Fine Polishing	1	Diamond	D1	1800g	60 D	DI water	160-220rpm	30-50s
	Cleaning								
5	Final Polishing	0.01	SiO2	ADS	1500g	50 D	DI water/ SOQ-12D	160-220rpm	30-40s
	Cleaning								



Remove Epoxy Polishing *Rough Polishing* *Middle Polishing* *Fine Polishing* *Final*

Note:

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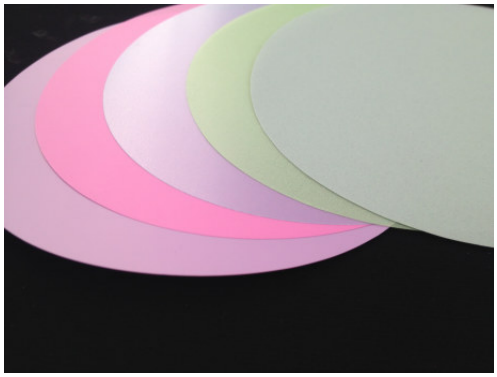
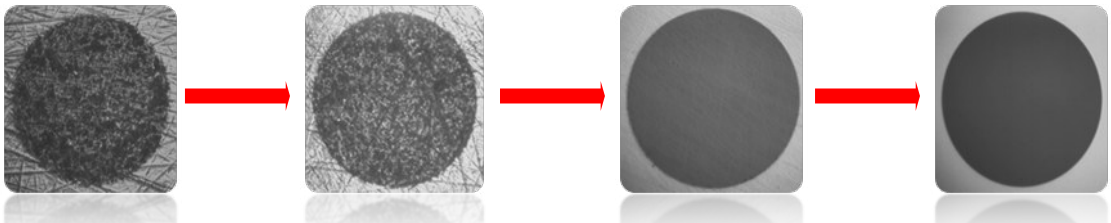


Seiko Instrument OFL-15(12UPC) :

Step		Polishing Film			Process				
		Micron	Mineral	Product ID	Pressure	Pad	Liquid	Speed	Time
1	Remove Epoxy	15/30	SiC/D	SC15/SC30 D30	By hand	n/a	Dry	n/a	40-60s
	Cleaning								
2	Rough Polishing	9	Diamond	D9	1800g	60 D	DI water	160-220rpm	40-60s
	Cleaning								
3	Fine Polishing	1	Diamond	D1	1800g	60 D	DI water	160-220rpm	40-60s
	Cleaning								
4	Final Polishing	0.01	SiO2	ADS	1500g	50 D	DI water/ SOQ-12D	140-220rpm	30-40s
	Cleaning								



Remove Epoxy *Rough Polishing* *Fine Polishing* *Final Polishing*

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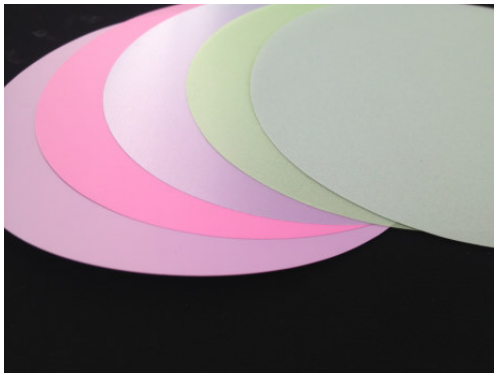
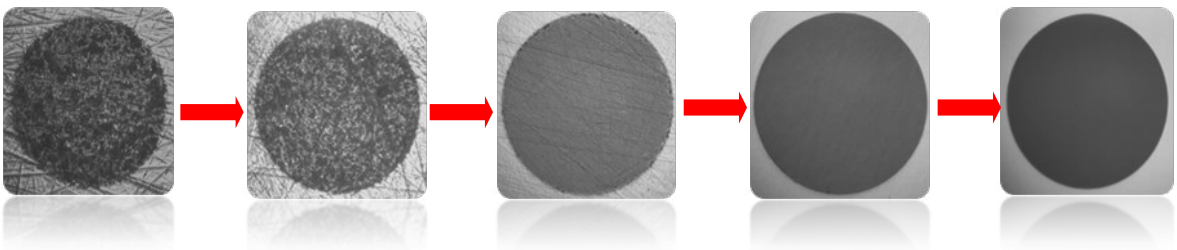


ULTRAPOL Polisher 1200:

Step		Polishing Film			Process	
		Micron	Mineral	Product ID	Pad	Liquid
1	Remove Epoxy	15/30	SiC/D	SC15/SC30/D30	Rubber pad	Dry
	Cleaning					
2	Rough Polishing	9	Diamond	D9	Rubber pad	DI water
	Cleaning					
3	Middle Polishing	3	Diamond	D3	Rubber pad	DI water
	Cleaning					
4	Fine Polishing	1	Diamond	D1	Rubber pad	DI water
	Cleaning					
5	Final Polishing	0.01	SiO2	ADS	Rubber pad	DI water/ SOQ-12D
	Cleaning					



Remove Epoxy Polishing *Rough Polishing* *Middle Polishing* *Fine Polishing* *Final*

Note:

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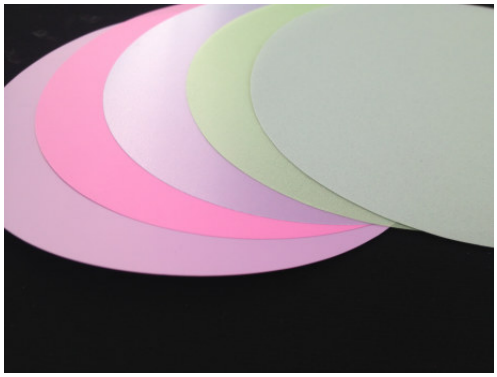
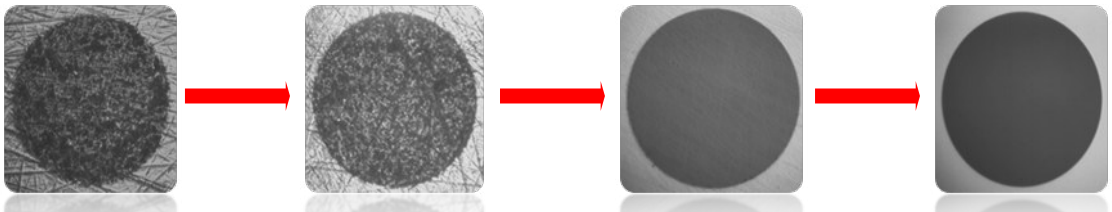


ULTRAPOL Polisher 1200:

Step		Polishing Film			Process	
		Micron	Mineral	Product ID	Pad	Liquid
1	Remove Epoxy	15/30	SiC	SC15/SC30	Rubber pad	Dry
	Cleaning					
2	Rough Polishing	9	Diamond	D9	Rubber pad	DI water
	Cleaning					
3	Fine Polishing	1	Diamond	D1	Rubber pad	DI water
	Cleaning					
4	Final Polishing	0.01	SiO2	ADS	Rubber pad	DI water/ SOQ-12D
	Cleaning					



Remove Epoxy *Rough Polishing* *Fine Polishing* *Final Polishing*

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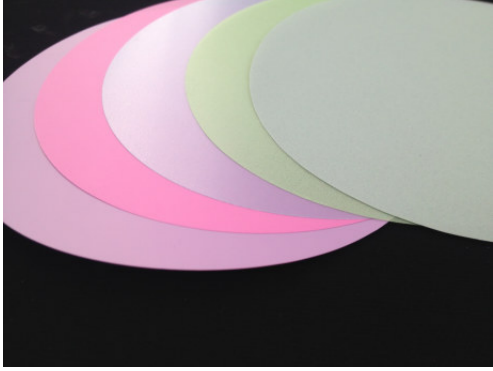
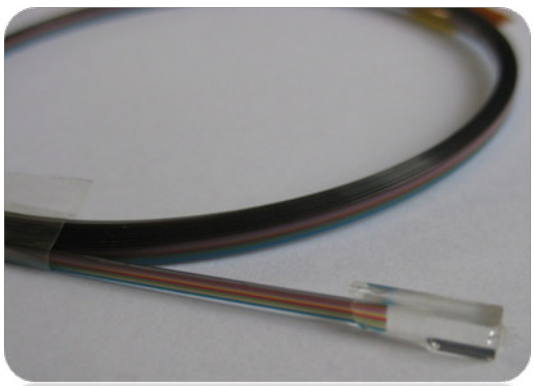
Suggested Process for Polishing FA



Seiko Giken SFP-550:

Step	Polishing Film	Polishing Liquid	Polishing Pad	Time
1 Remove Epoxy	SC30	Dry	Glass/Stainless Steel	0.5-1min
2 Angle Polishing	D30 /D15	DI water	Glass/Stainless Steel	3-5 min
3 Rough Polishing	D9	DI water	Glass/Stainless Steel	3-5 min
4 Middle Polishing	D3	DI water	Glass/Stainless Steel	2-3 min
5 Fine Polishing	D1	DI water	Glass/Stainless Steel	1-2min
6 Final Polishing	CO0.3/AO0.3	CO0.3/AO0.3 Slurry	Glass/Stainless Steel	1-2 min



Suggested Process for Polishing FA

Seiko Instrument OFL-12: （Speed: 120-150rpm）

Step	Polishing Film	Polishing Liquid	Polishing Pad	Pressure	Time
1 Remove Epoxy	SC30	Dry	Glass/Stainless Steel	Point 2	0.5-1 min
2 Angle Polishing	D30 /D15	DI water	Glass/Stainless Steel	Point 3	3-5 min
3 Rough Polishing	D9	DI water	Glass/Stainless Steel	Point 3	3-5 min
4 Middle Polishing	D3	DI water	Glass/Stainless Steel	Point 3	2-3 min
5 Fine Polishing	D1	DI water	Glass/Stainless Steel	Point 3	1-2 min
6 Final Polishing	CO0.3/AO0.3	CO0.3/AO0.3 Slurry	Glass/Stainless Steel	Point 3	1-2 min